

5.90-6.40GHz 8-Watt Internally Matched Power FET

FEATURES

- 5.90–6.40GHz Bandwidth
- Input/Output Impedance Matched to 50 Ohms
- +39.5 dBm Output Power at 1dB Compression
- 10.0 dB Power Gain at 1dB Compression
- 37% Power Added Efficiency
- -46 dBc IM3 at PO = 28.5 dBm SCL
- 100% Tested for DC, RF, and R_{TH}



ELECTRICAL CHARACTERISTICS (T_a = 25°C)



Caution! ESD sensitive device.

SYMBOL	PARAMETERS/TEST CONDITIONS ¹	MIN	TYP	MAX	UNITS
P _{1dB}	Output Power at 1dB Compression $f = 5.9-6.4GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 2200\text{mA}$	38.5	39.5		dBm
G _{1dB}	Gain at 1dB Compression $f = 5.9-6.4$ GHz $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 2200$ mA	9.0	10.0		dB
ΔG	Gain Flatness $f = 5.9-6.4$ GHz $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 2200$ mA			±0.6	dB
PAE	Power Added Efficiency at 1dB Compression V _{DS} = 10 V, I _{DSQ} ≈ 2200mA		37		%
Id _{1dB}	Drain Current at 1dB Compression f = 5.9-6.4GHz		2200	2600	mA
IM3	Output 3rd Order Intermodulation Distortion Δf = 10 MHz 2-Tone Test; Pout = 28.5 dBm S.C.L ² V_{DS} = 10 V, $I_{DSQ} \approx 65\%$ IDSS f =6.4GHz	-43	-46		dBc
I _{DSS}	Saturated Drain Current $V_{DS} = 3 \text{ V}, V_{GS} = 0 \text{ V}$		4000	4500	mA
V_P	Pinch-off Voltage $V_{DS} = 3 \text{ V}, I_{DS} = 40 \text{ mA}$		-2.5	-4.0	V
R _{TH}	Thermal Resistance ³		3.5	4.0	°C/W

Note: 1. Tested with 100 Ohm gate resistor.

- 2. S.C.L. = Single Carrier Level.
- 3. Overall Rth depends on case mounting.

ABSOLUTE MAXIMUM RATING FOR EFE

SYMBOLS PARAMETERS		ABSOLUTE ¹	CONTINUOUS ²	
Vds	Drain-Source Voltage	15V	10V	
Vgs Gate-Source Voltage		-5V	-4V	
lgf Forward Gate Current		96mA	28.8mA	
Igr Reverse Gate Current		-19.2mA	-4.8mA	
Pin	Pin Input Power		@ 3dB Compression	
Tch	Channel Temperature	175C	175C	
Tstg	Tstg Storage Temperature		-65C to +175C	
Pt	Pt Total Power Dissipation		37.5W	

Note: 1. Exceeding any of the above ratings may result in permanent damage.

2. Exceeding any of the above ratings may reduce MTTF below design goals.

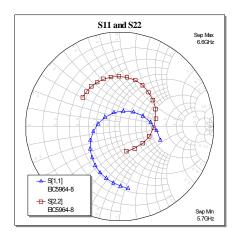


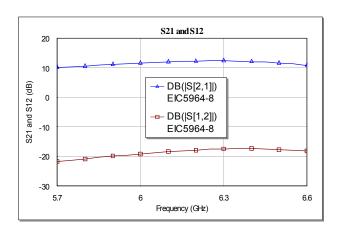


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PERFORMANCE DATA

Typical S-Parameters (T= 25°C, 50Ω system, de-embedded to edge of package) V_{DS} = 10 V, I_{DSQ} ≈ 2200mA





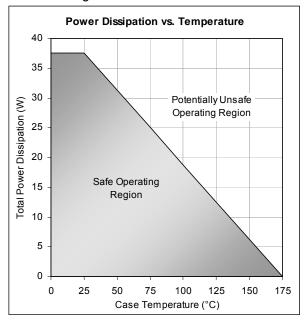
FREQ	S	11	S	S21 S12		12	S22	
(GHz)	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
5.0	0.873	-7.73	1.9865	102.43	0.0385	50.45	0.4069	-90.78
5.2	0.8439	-25.93	2.285	77.92	0.0467	23.43	0.4003	-128.98
5.4	0.7893	-46.35	2.6094	51.4	0.0592	-4.16	0.4285	-166.69
5.6	0.7151	-69.29	2.9628	23.77	0.0737	-33.07	0.4765	158.39
5.8	0.6028	-96.47	3.3734	-5.88	0.0912	-62.69	0.5213	125.52
6.0	0.444	-131.54	3.7964	-39.07	0.1107	-96.25	0.5321	90.88
6.2	0.2308	173.31	4.0744	-76.09	0.1282	-133.24	0.4733	49.87
6.4	0.2091	46.37	4.0033	-116.4	0.1362	-173.52	0.3603	-2.01
6.6	0.455	-18.8	3.4617	-156.9	0.1237	147.8	0.2712	-75.07
6.8	0.6333	-56.77	2.6951	167.51	0.1009	112.66	0.3134	-142.54
7.0	0.7311	-85.42	2.035	136.97	0.0814	83.64	0.4055	176.45

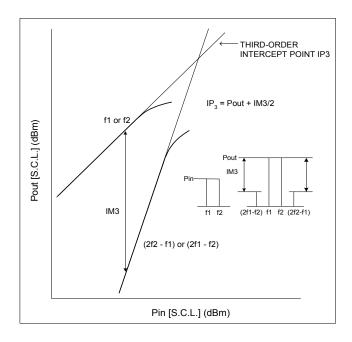




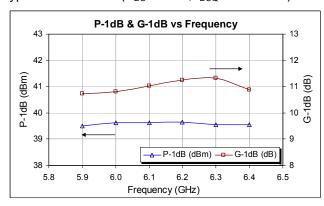
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Power De-rating Curve and IM3 Definition

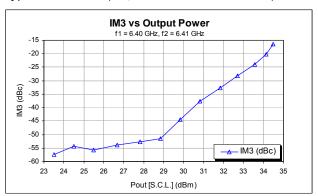




Typical Power Data ($V_{DS} = 10 \text{ V}$, $I_{DSQ} = 2200 \text{ mA}$)



Typical IM3 Data ($V_{DS} = 10 \text{ V}$, $I_{DSQ} \approx 65\% \text{ IDSS}$)



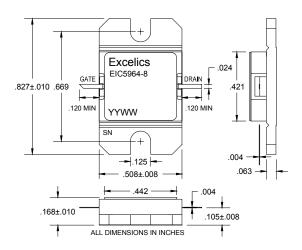


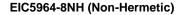
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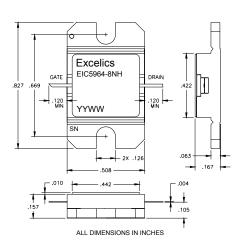
PACKAGES OUTLINE

Dimensions in inches, Tolerance + .005 unless otherwise specified

EIC5964-8 (Hermetic)









Caution! ESD sensitive device.



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ORDERING INFORMATION

Part Number	Packages	Grade ¹	f _{Test} (GHz)	P _{1dB} (min)	$IM_3 (min)^2$
EIC5964-8	Hermetic	Industrial	5.90-6.40GHz	38.5	-43
EIC5964-8NH	Non-Hermetic	Industrial	5.90-6.40GHz	38.5	-43

Notes:

- 1. Contact factory for military and hi-rel grades.
- 2. Exact test conditions are specified in "Electrical Characteristics" table.

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